



PATENT

#9/Ltr to
DRAFTSMAN
R. Tyson
2/16/01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Chen et al

(attorney docket: TIS-25912)

Serial No. 09/115,444

Group Art Unit: 2841

Filed: July 14, 1998

Examiner: Foster, D.

For: High Density Internal Ball Grid Array Integrated Circuit Package

REQUEST FOR APPROVAL TO AMEND DRAWINGS

Commissioner for Patents

Washington, DC 20231

Dear Sir:

Approval to amend the drawings of the above-referenced application as shown in red in the attached drawing is respectfully requested.

In the drawings:

In Figure 2, add a second line identifier from reference numeral "70" to the lower cross-hatched horizontally extending member as shown in red in the attached.

REMARKS

Approval to amend the drawings in the above-referenced application is respectfully requested, and is submitted in response to a request by the Examiner to correct the drawings as follows. Specifically, the originally-filed Figure 2 illustrates a printed circuit board 70. However, the line identifier from reference numeral "70" is directed only to the upper cross-hatched horizontally extending member. The Specification states, at page 14, lines 4-5:

The printed circuit board 70 depicted has two layers, a top layer 76 and a bottom layer 78.

In view of this statement, the Examiner has objected to Figure 2 because the reference line is "drawn to only [the] top portion of the" printed circuit board. Accordingly, the proposed amendment also draws a reference line to the bottom portion of the printed circuit board.

Approval to so amend the drawings is respectfully requested.

Respectfully submitted,



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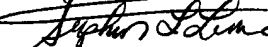
CERTIFICATE OF MAILING

37 C.F.R. § 1.8

The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to:

Commissioner for Patents
Washington, DC 20231

on January 16, 2001



Stephen L. Levine
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